

Call for papers

1. Title of Special Issue:

Signal Collection, Processing, and System Integration in Automation Applications 2026

2. Topic Description of Special Issue:

Automation systems based on signal collection, processing, and system integration have emerged as a multidisciplinary frontier of science and engineering. The high demand for industrial automation has motivated researchers to explore advanced technology development using a wide variety of sensors in industry. Accordingly, sensor-related signal processing algorithms have acquired a critical role in automation fields. In addition, Industry 4.0 techniques are leading engineering into a new era. More complex systems, such as automatization, robotics, mechatronics, measurement, and control systems, can now be enhanced more efficiently by using signal collection, processing, system integration and artificial intelligence (AI) approaches. For this Special Issue, submissions of papers based on novel methodologies and implementations, creative and innovative automation systems, and integrated engineering associated with these topics are all welcome.

3. Prospective authors are invited to submit original and unpublished work on the following research topics related to but not limited to this Special Issue.

- Sensor-based science and application technology
- Automatic sensor signal measurement
- Sensor signal processing using artificial network models
- Sensor signal collection and processing
- Image signal processing technology
- Sensor-based measurement technology
- Sensor applications in intelligent control
- System integration using sensor signals
- Remote sensor networks in automation monitoring and control
- Sensor applications in Industry 4.0
- AI applications in signal processing and automation control

4. Special Issue organizer:

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5. Submission deadline: December 31, 2026

Please refer to Section 4 of the Instructions to Authors for detailed information on specific price amounts on our website below.

<https://sensors.myu-group.co.jp/permanent/Instructions%20to%20authors2019%20EN.pdf>

If you have any questions, please feel free to contact the editorial staff at the address below.

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